

Title (en)

METHOD FOR PRODUCING THIN SUBSTRATE LAYERS

Title (de)

VERFAHREN ZUR FERTIGUNG VON DÜNNEN SUBSTRATSCHICHTEN

Title (fr)

PROCEDE POUR LA PRODUCTION DE COUCHES DE SUBSTRAT MINCES

Publication

EP 1090422 A1 20010411 (DE)

Application

EP 99939373 A 19990622

Priority

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Abstract (en)

[origin: DE19840421A1] A thin substrate layer is produced from two bonded substrates (1, 2) having interface channel recesses (5) for etchant penetration. A thin substrate layer is produced by: (a) bonding two substrate front faces using one or more intermediate bonding layers (3, 4), at least one of the bonding layers or the front face of one of the substrates (1, 2) having channel-like recesses (5) which allow sideways penetration of an etchant; (b) thinning one substrate (1) down to a substrate layer (1a); and (c) detaching the substrate layer from the other substrate (2) by introducing etchant into the recesses. An Independent claim is also included for a substrate structure resulting from step (a) of the above process.

IPC 1-7

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IPC 8 full level

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CPC (source: EP US)

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